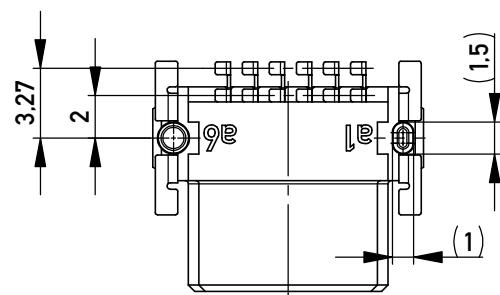
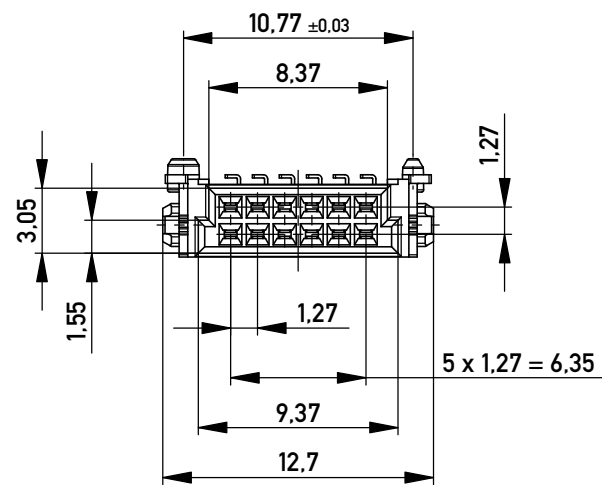
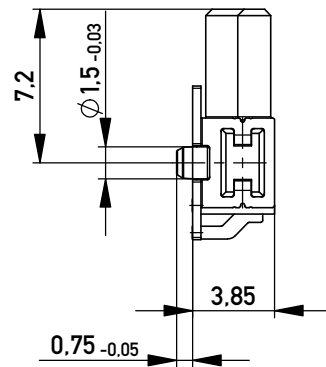
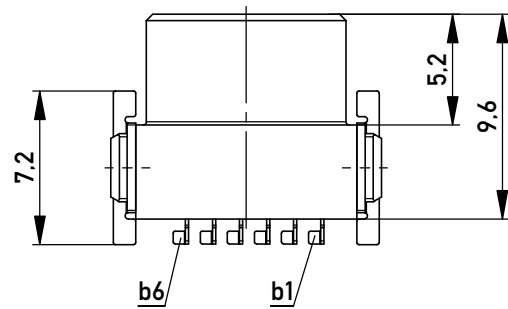
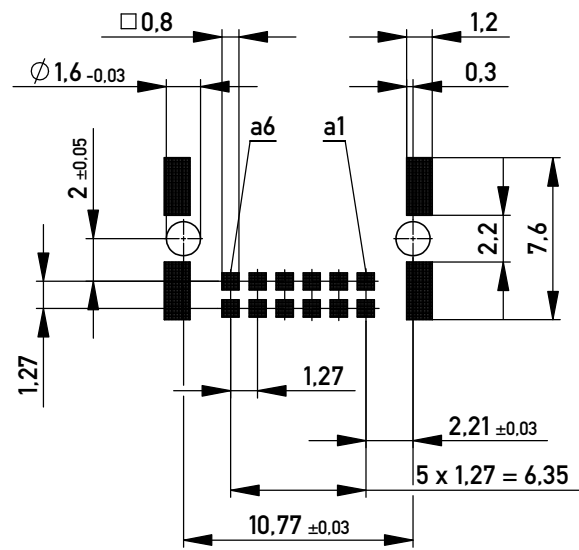
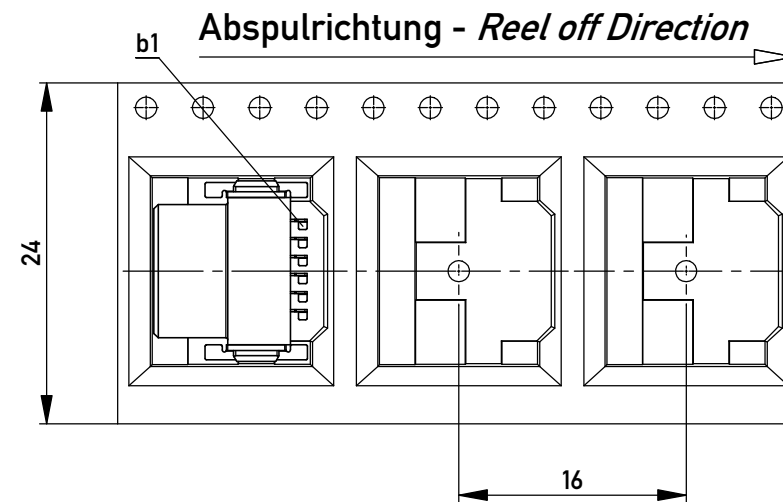
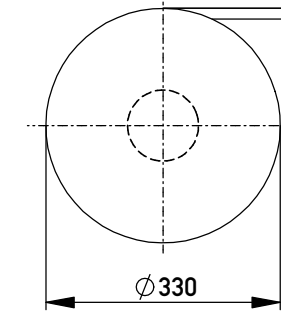


Leiterplatten-Layout Vorschlag für SMT
PCB-Layout Proposal for SMT



Verpackt im Gurt nach DIN IEC 60286-3
Tape on Reel Packaging according to DIN IEC 60286-3
Verpackungseinheit: 560 Stück
Packaging unit: 560 pcs



Anforderungsstufe 1
Performance Level 1

Kontaktbereich vergoldet
Mating Area gold plating

Anschlussbereich verzinkt 4-6 µm
Terminal Area 4-6 µm tin plating

Koplanarität der Anschlüsse ≤ 0,1 mm
Coplanarity Area of Termination ≤ 0.1 mm

BA7-03 - Standard Bauhöhe
type7-03 - standard assembly height

Information: All rights reserved. Only for Information. To ensure that this is the latest version of this drawing, please contact one of the ERNI companies before using.	Tolerances All Dimensions in mm	Scale 3:1	Designation Federl. SMC-Q 12-SMD-BA7-03 Female SMC-Q 12-SMD-type7-03	
	Subject to modification without prior notice. Drawing will not be updated.		100302940001	
f	23.04.2014	www.ERNI.com	K	
Index	Date	ERNI	A3	
Class			SMCQ	

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